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Variant: None

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### LM5121 Boost

Designator	Description	Manufacturer	PartNumber	Quantity
IPC1	Printed Circuit Board	Any	PMP9372	1
C1	CAP, CERM, 680pF, 50V, +/-5%, C0G/NP0, 0603	MuRata	GRM1885C1H681JA01D	1
C2, C3, C4	CAP, CERM, 22uF, 25V, +/-10%, X5R, 1206	MuRata	GRM31CR61E226KE15L	3
C5, C6, C7	CAP, CERM, 47uF, 25V, +/-20%, X5R, 1206	TDK	C3216X5R1E476M160AC	3
C8	CAP, AL, 4700uF, 25V, +/-20%, TH	Nichicon	UKA1E472MHD	1
C9	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0402	MuRata	GRM1555C1H101JA01D	1
C10, C18	CAP, CERM, 0.1uF, 16V, +/-10%, X7R, 0603	MuRata	GRM188R71C104KA01D	2
C11	CAP, CERM, 0.01uF, 50V, +/-10%, X7R, 0402	MuRata	GRM155R71H103KA88D	1
C12, C13	CAP, CERM, 1uF, 25V, +/-10%, X5R, 0402	TDK	C1005X5R1E105K050BC	2
C14	CAP, CERM, 0.15uF, 10V, +/-10%, X5R, 0402	MuRata	GRM155R61A154KE19D	1
C15	CAP, CERM, 1uF, 25V, +/-10%, X5R, 0603	MuRata	GRM188R61E105KA12D	1
C16	CAP, CERM, 0.01uF, 25V, +/-10%, X7R, 0402	MuRata	GRM155R71E103KA01D	1
C17	CAP, CERM, 470pF, 50V, +/-5%, C0G/NP0, 0402	TDK	C1005C0G1H471J	1
D2	Diode, Schottky, 100V, 1A, PowerDI123	Diodes Inc.	DFLS1100-7	1
D3, R5, R7	RES, 0 ohm, 5%, 0.063W, 0402	Vishay-Dale	CRCW04020000Z0ED	3
D5, D6, D7	Diode, Ultrafast, 100V, 0.25A, SOD-323	NXP Semiconductor	BAS316,115	3
FID1, FID2, FID3	Fiducial mark. There is nothing to buy or mount.	N/A	N/A	3
H1, H2, H3, H4	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	B&F Fastener Supply	NY PMS 440 0025 PH	4
H5, H6, H7, H8	Standoff, Hex, 0.5"L #4-40 Nylon	Keystone	1902C	4
J1, J2, J3, J4	Standard Banana Jack, Uninsulated, 8.9mm	Keystone	575-8	4
J5, J6, J7	Connector, RF Jack, Vertical, Gold, SMD	Amphenol	A-1JB	3
L1	Inductor, Shielded Drum Core, Ferrite, 2.2uH, 12.5A, 0.0044 ohm, SMD	Würth Elektronik eiSos	7443340220	1
LBL1	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	Brady	THT-14-423-10	1
Q1, Q3	MOSFET, N-CH, 30V, 60A, SON 3.3x3.3mm	Texas Instruments	CSD17309Q3	2
Q2	MOSFET, N-CH, 30V, 100A, LPAK	NXP Semiconductor	PSMN1R2-30YLC	1
R1	RES, 1.0 ohm, 5%, 0.125W, 0805	Vishay-Dale	CRCW08051R00JNEA	1
R2	RES, 0.01 ohm, 1%, 1W, 2010	Stackpole Electronics Inc	CSRN2010FK10L0	1
R3, R4	RES, 100 ohm, 5%, 0.063W, 0402	Vishay-Dale	CRCW0402100RJNED	2
R6	RES, 49.9 ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW040249R9FKED	1
R8, R13	RES, xxx ohm, x%, xW, [PackageReference]	Used in BOM report	DNP1	2
R9, R19, R20	RES, 100k ohm, 5%, 0.063W, 0402	Vishay-Dale	CRCW0402100KJNED	3
R10	RES, 23.7k ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW040223K7FKED	1
R11	RES, 20.0k ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW040220K0FKED	1
R12	RES, 15.0k ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW040215K0FKED	1
R14	RES, 2.00k ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW04022K00FKED	1
R15	RES, 100k ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW0402100KFKED	1
R16, R17, R18	RES, 49.9 ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW060349R9FKEA	3
R21	RES, 162k ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW0402162KFKED	1
R22	RES, 604 ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW0402604RFKED	1
R23	RES, 4.02k ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW04024K02FKED	1
TP1, TP2, TP10	Test Point, Multipurpose, Red, TH	Keystone	5010	3
TP3, TP4, TP7, TP13	Test Point, Multipurpose, Black, TH	Keystone	5011	4

<b>Designator</b>	<b>Description</b>	<b>Manufacturer</b>	<b>PartNumber</b>	<b>Quantity</b>
TP5, TP6, TP8, TP9, TP11, TP12	Test Point, Multipurpose, White, TH	Keystone	5012	6
U1	Wide Input Synchronous Boost Controller with Disconnection Switch Control, PWP0020A	Texas Instruments	LM5121MH/NOPB	1
U2	IC, High Voltage, Over-Under Voltage Supervisory	TI	TPS3700DDC	1
Z1	Diode, Zener, 2.4V, Sharp Knee, SOD-323	Diodes Inc.	CMDZ2L4	1

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